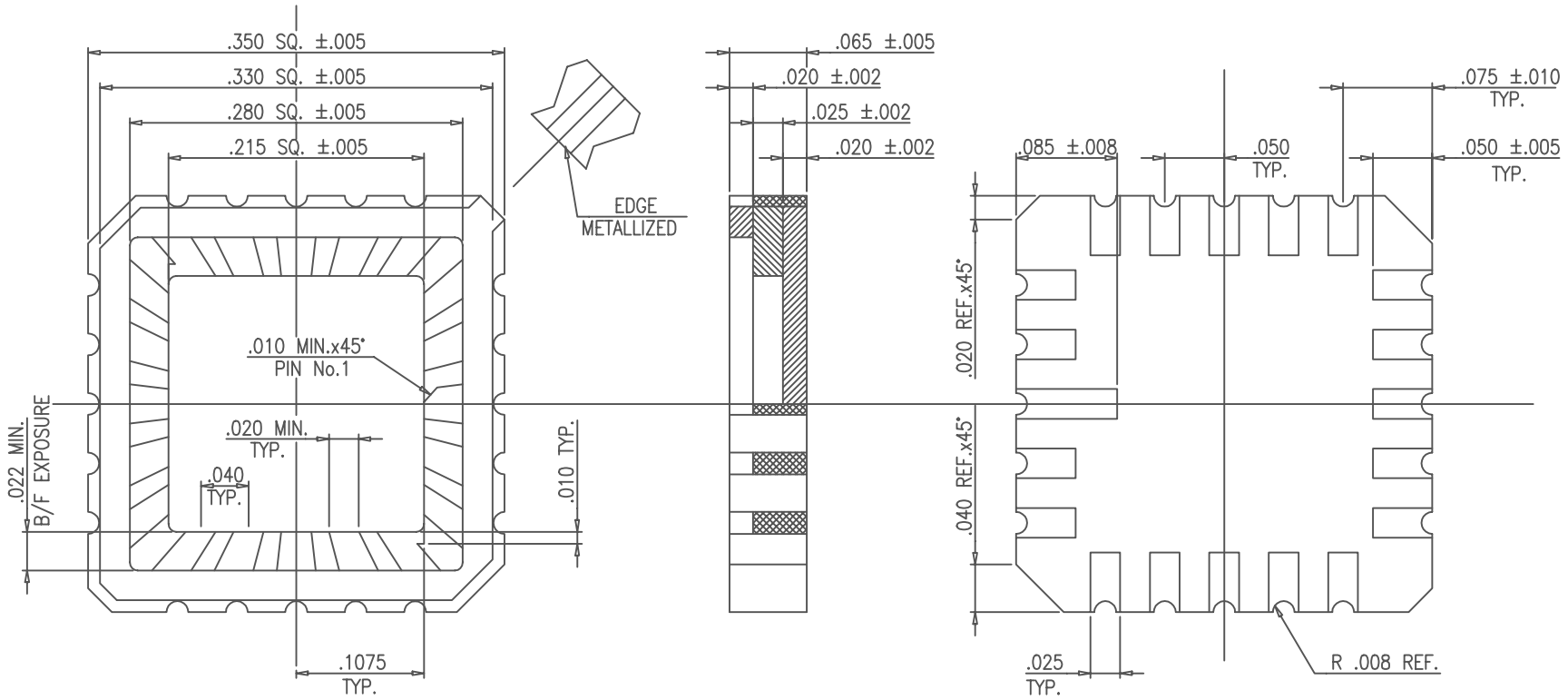

NOTES;

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN. THK. OVER NICKEL PLATED.
2. SEAL RING FLATNESS .003 MAX.
3. SEAL RING AND DIE ATTACH PAD ARE NOT GROUND TO A LEAD.

S=0
D=0

AN-20C

MODIFICATIONS					
CHANGE	DATE	DRAWN	CHECKED	APPROVED	

NAME 20LEAD CHIP CARRIER (.215 SQ. CAV.)

SCALE 10/1

MATERIAL KYOCERA A-440

TOLERANCES: UNLESS OTHERWISE SPECIFIED ±1% N.L.T ±.005 THIRD ANGLE PROJECTION

DRAWN	CHECKED	APPROVED	DATE
S.M	UE. K.H	M.S	MAR.16.'99

KYOCERA

KYOCERA CORPORATION
KYOTO JAPAN

DRAWING NO. PB-23741

SHEET 1/1